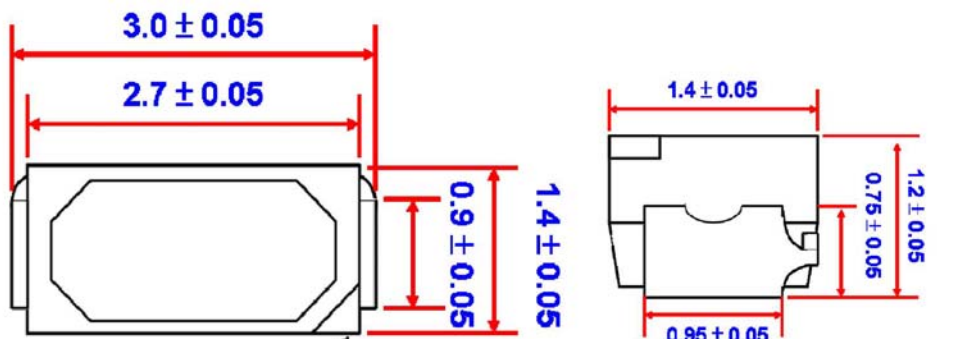


SURFACE MOUNT WHITE LED TOP VIEW 3.0 X 1.4 X 1.2mm

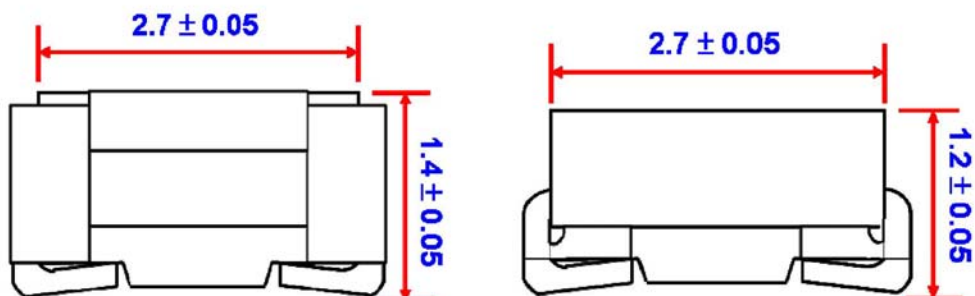
FEATURES

- TOP VIEW WHITE
- LED (3.0 x 1.4 x 1.2mm)
- WHITE SMT PACKAGE
- LEAD FRAME PACKAGE WITH INDIVIDUAL 2-PINS
- GaN-BASED LED WITH YELLOW PHOSPHOR
- WIDE VIEW ANGLE (X: 120°/Y: 120°)
- IR REFLOW SOLDERING
- ESD PROTECTION
- Pb FREE

DIMENSIONS

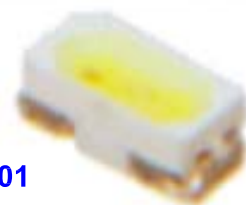


Anode mark



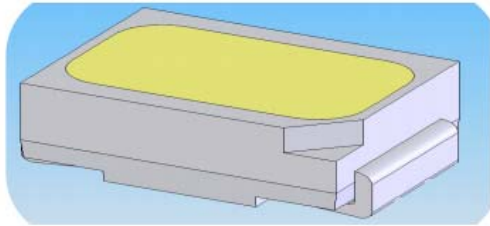
Polarity

UNIT: mm



JKL PART NO.: ZSM-T3014-W-01

DRAWN BY L. WENGSTROM		DRAWING NO. ZSM-T3014-W-01	
APPV'D BY L.R.	DATE 9/27/11	RELEASED DATE 9/27/11	REVISION DATE
			REV. NO.
			SHEET 1 OF 5



SURFACE MOUNT WHITE LED TOP VIEW 3.0 X 1.4 X 1.2mm

SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)
(LED die)

ITEM	SYMBOL	ABSOLUTE MAXIMUM RATING	UNIT
Forward Current	I_F	30	mA
Pulse Forward Current*	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	120	mW
Operating Temperature	T_{opr}	-30 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Soldering Temperature	T_{sld}	Reflow Soldering: 260° C for 10 secs Hand Soldering: 350° C for 3 secs	

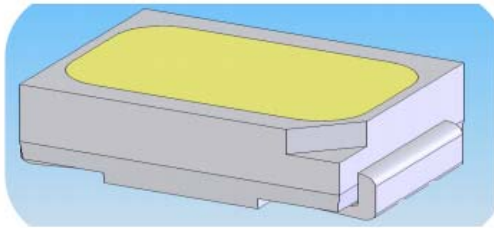
(Zener diode)

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Reverse Leakage Current	I_R	$V_R = 5V$	---	0.5	uA
Zener Voltage	V_Z	$I_Z = 5mA$	5.8	6.8	V
Forward Voltage	V_F	$I_F = 20mA$	---	1.2	V

* I_{FP} Conditions: Pulse Width $\leq 10msec$, and duty $\leq 1/10$

ELECTRICAL & OPTICAL OPERATING CHARACTERISTICS (TA = 25°C)

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT	
Luminous Intensity	E	I_V	$I_F = 20mA$	1400	1500	mcd
	F			1500	1600	
	G			1600	1700	
	H			1700	1800	
	I			1800	1900	
	J			1900	2000	
	K			2000	2100	
	L			2100	2200	



SURFACE MOUNT WHITE LED TOP VIEW 3.0 X 1.4 X 1.2mm

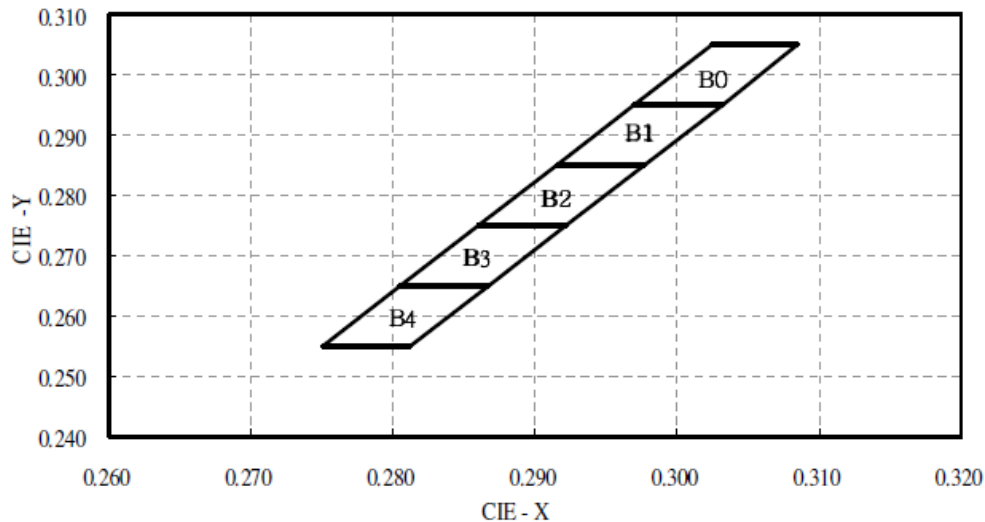
BIN RANGE OF CHROMATICITY COORDINATES

	CIE-X	CIE-Y		CIE-X	CIE-Y
B0	0.3100	0.3050	B3	0.2935	0.2750
	0.3045	0.2950		0.2880	0.2650
	0.2970	0.2950		0.2805	0.2650
	0.3025	0.3050		0.2860	0.2750
B1	0.3045	0.2950	B4	0.2880	0.2650
	0.2990	0.2850		0.2825	0.2550
	0.2915	0.2850		0.2750	0.2550
	0.2970	0.2950		0.2805	0.2650
B2	0.2990	0.2850			
	0.2935	0.2750			
	0.2860	0.2750			
	0.2915	0.2850			

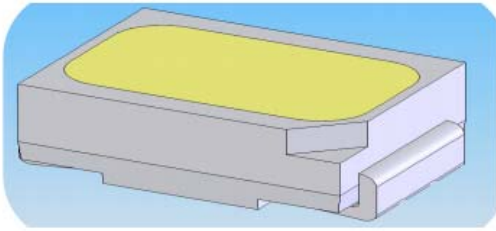
*If color binning is required, only one color group is allowed for each chip within a reel.

Chromaticity coordinate groups are measured with an accuracy of ± 0.01 .

*Color coordinate is derived from the CIE 1931 chromaticity.



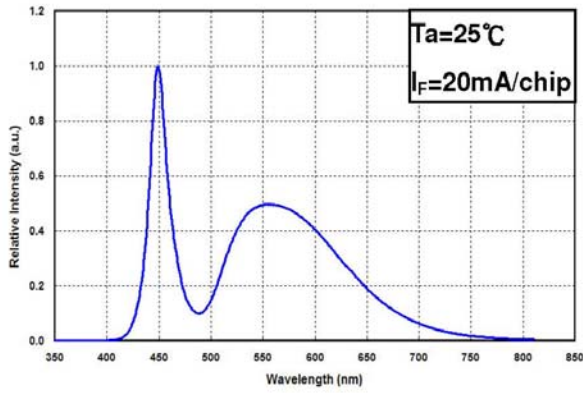
**CHROMATICITY
DIAGRAM**



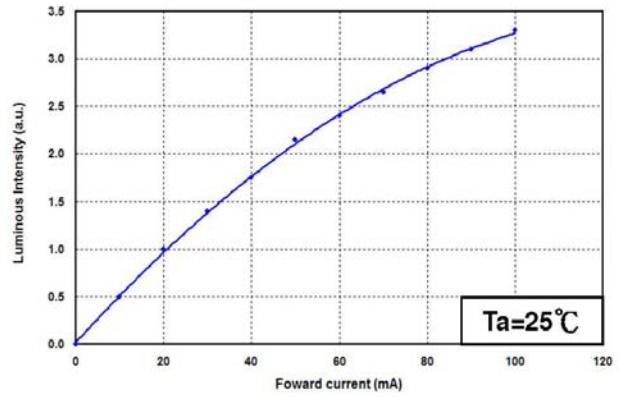
SURFACE MOUNT WHITE LED TOP VIEW 3.0 X 1.4 X 1.2mm

TYPICAL ELECTRO-OPTICAL CHARACTERISTICS CURVES

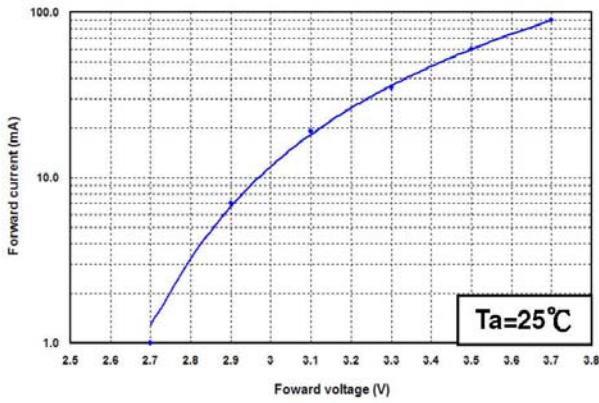
Spectrum



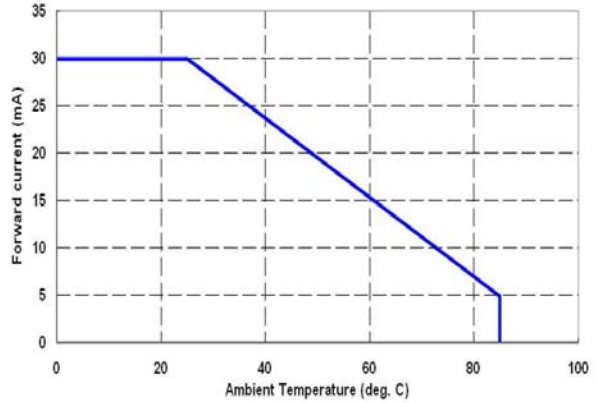
Luminous intensity — I_f



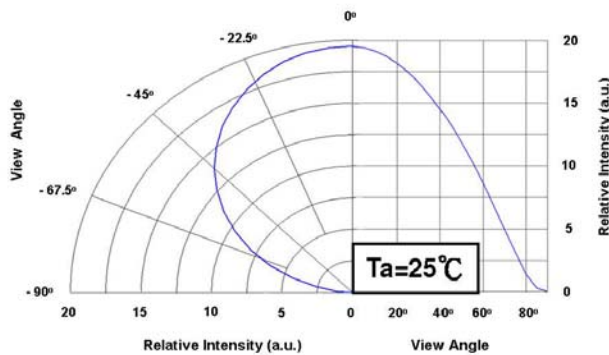
$I_f - V_f$

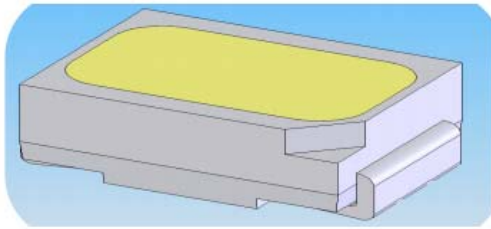


$I_f - T_a$



Radiation Pattern

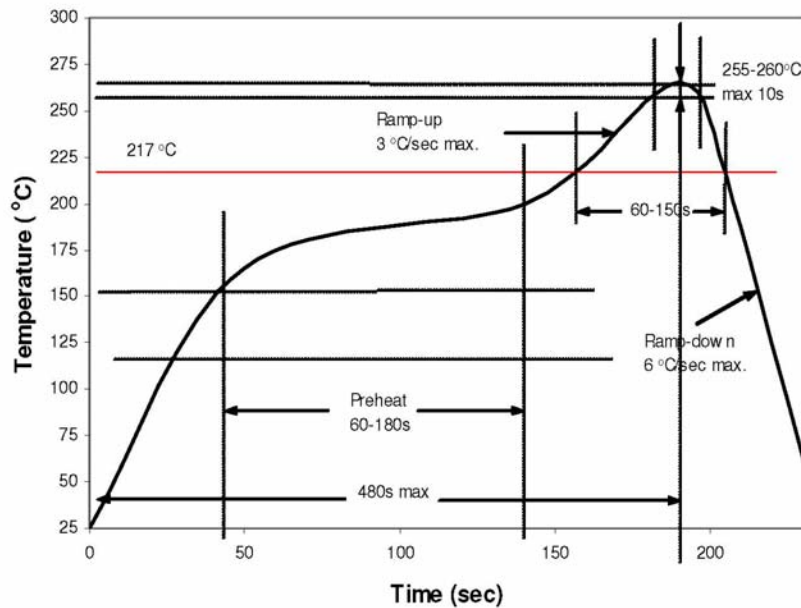




SURFACE MOUNT WHITE LED TOP VIEW 3.0 X 1.4 X 1.2mm

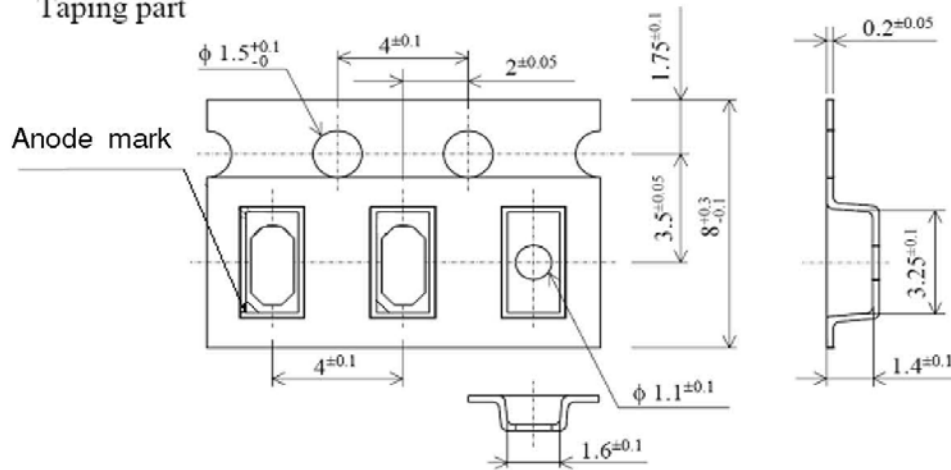
LEAD-FREE SOLDER

Classification Reflow Profile (JEDEC J-STD-335C)



PACKAGING: 2500 pcs/REEL

Taping part



NOTES:

1. STORE IN ORIGINAL MOISTURE PROOF PACKAGING.
2. PACKAGING SHOULD BE STORED AT 30°C OR LESS AND AT 60% RH OR LESS.
3. LED SHOULD BE SOLDERED WITHIN 168 HOURS AFTER OPENING.
4. LED'S ARE STATIC SENSITIVE DEVICES. DO NOT HANDLE WITHOUT APPROPRIATE STATIC PROTECTION.
5. CLEAN ONLY WITH ISOPROPYL ALCOHOL. DO NOT USE ULTRASONIC CLEANING.
6. **CAUTION:** DO NOT LOOK DIRECTLY INTO LIT LED. INJURY TO EYES CAN OCCUR.